

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

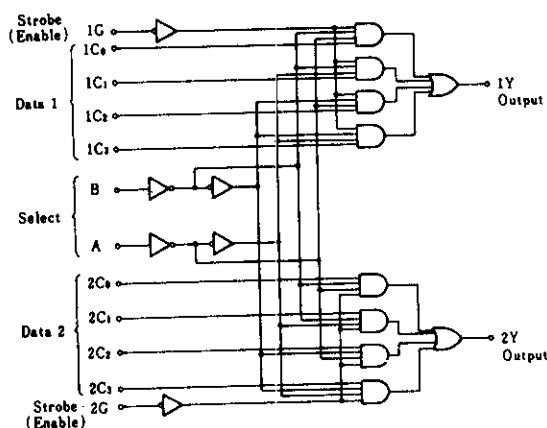
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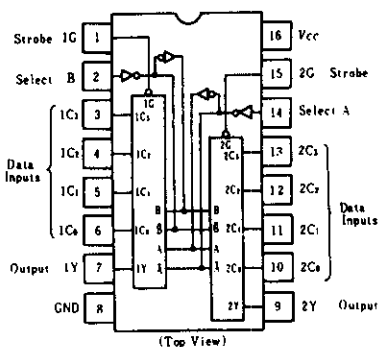
HD74LS153 • Dual 4-Line to 1-Line Data Selectors/Multiplexers

This data selector/multiplexer contains inverters and drivers to supply fully complementary, on-chip, binary decoding data selection to the AND-OR-INVERT gates. Separate strobe inputs are provided for each of the two four-line sections.

■ BLOCK DIAGRAM



■ PIN ARRANGEMENT



■ FUNCTION TABLE

Inputs							Outputs
Select		Data				Strobe	
B	A	C ₀	C ₁	C ₂	C ₃	G	Y
×	×	×	×	×	×	H	L
L	L	L	×	×	×	L	L
L	L	H	×	×	×	L	H
L	H	×	L	×	×	L	L
L	H	×	H	×	×	L	H
H	L	×	×	L	×	L	L
H	L	×	×	H	×	L	H
H	H	×	×	×	L	L	L
H	H	×	×	×	H	L	H

H; high level, L; low level, X; irrelevant

■ ELECTRICAL CHARACTERISTICS ($T_a = -20 \sim +75^\circ\text{C}$)

Item	Symbol	Test Conditions	min	typ*	max	Unit
Input voltage	V_{IH}		2.0	—	—	V
	V_{IL}		—	—	0.8	V
Output voltage	V_{OH}	$V_{CC}=4.75\text{V}$, $V_{IH}=2\text{V}$, $V_{IL}=0.8\text{V}$, $I_{OH}=-400\mu\text{A}$	2.7	—	—	V
	V_{OL}	$V_{CC}=4.75\text{V}$, $V_{IH}=2\text{V}$, $I_{OL}=4\text{mA}$	—	—	0.4	V
		$V_{IL}=0.8\text{V}$, $I_{OL}=8\text{mA}$	—	—	0.5	
Input current	I_{IH}	$V_{CC}=5.25\text{V}$, $V_I=2.7\text{V}$	—	—	20	μA
	I_{IL}	$V_{CC}=5.25\text{V}$, $V_I=0.4\text{V}$	—	—	-0.4	mA
	I_I	$V_{CC}=5.25\text{V}$, $V_I=7\text{V}$	—	—	0.1	mA
Short-circuit output current	I_{OS}	$V_{CC}=5.25\text{V}$	-20	—	-100	mA
Supply current**	I_{CCL}	$V_{CC}=5.25\text{V}$	—	6.2	10	mA
Input clamp voltage	V_{IK}	$V_{CC}=4.75\text{V}$, $I_{IN}=-18\text{mA}$	—	—	-1.5	V

* $V_{CC}=5\text{V}$, $T_a=25^\circ\text{C}$

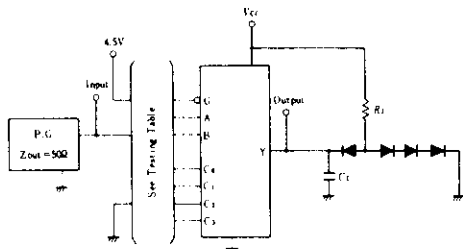
** I_{CC} is measured with all outputs open and all inputs grounded.

■SWITCHING CHARACTERISTICS ($V_{CC}=5V$, $T_a=25^{\circ}C$)

Item	Symbol	Inputs	Outputs	Test Conditions	min	typ	max	Unit
Propagation delay time	t_{PLH}	Data	Y	$C_L=15pF$, $R_L=2k\Omega$	—	10	15	ns
	t_{PHL}	Data	Y		—	17	26	ns
	t_{PLH}	Select	Y		—	19	29	ns
	t_{PHL}	Select	Y		—	25	38	ns
	t_{PLH}	Strobe	Y		—	16	24	ns
	t_{PHL}	Strobe	Y		—	21	32	ns

■TESTING METHOD

1) Test Circuit



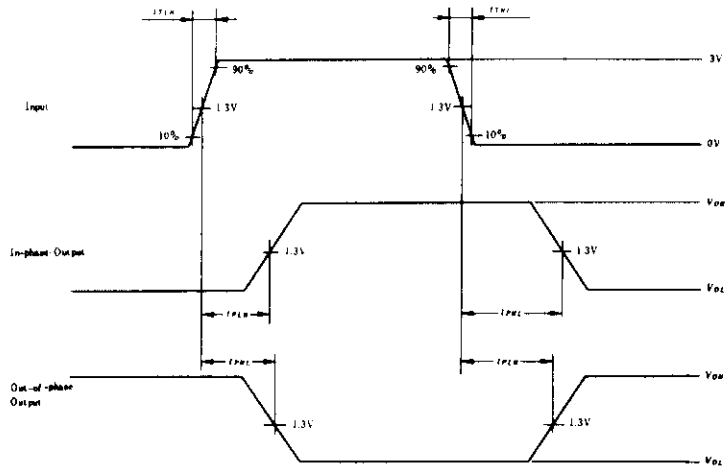
- Notes) 1. C_L includes probe and jig capacitance.
2. All diodes are 1S2074 (H).

2) Testing Table

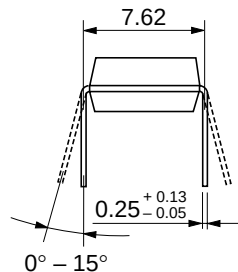
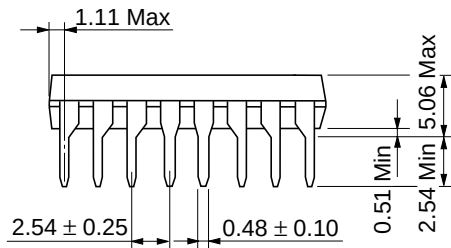
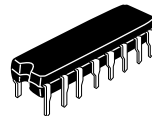
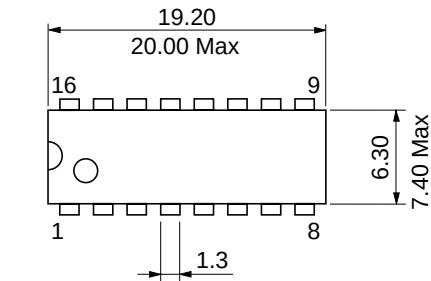
Item	Inputs							Output	
	B	A	C_0	C_1	C_2	C_3	G	Y	
t_{PLH}	GND	GND	IN	X	X	X	GND	OUT	
	GND	4.5V	X	IN	X	X	GND	OUT	
	4.5V	GND	X	X	IN	X	GND	OUT	
	4.5V	4.5V	X	X	X	IN	GND	OUT	
t_{PHL}	GND	IN	GND	4.5V	X	X	GND	OUT	
			4.5V	GND					
	IN	GND	GND	X	4.5V	X	GND	OUT	
			4.5V	GND	GND	X	GND	OUT	
	GND	GND	4.5V	X	X	X	IN	OUT	

X: "4.5V" or "GND"

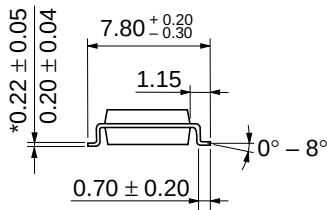
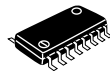
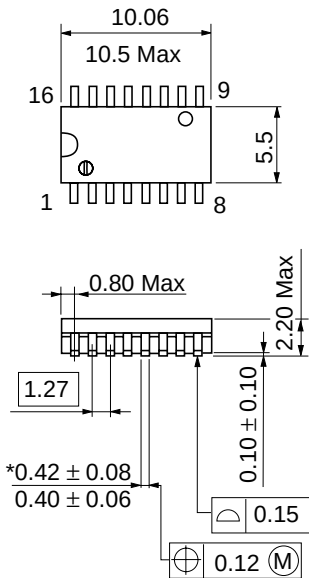
Waveform



Input pulse; $t_{TLH} \leq 15ns$, $t_{THL} \leq 6ns$,
 $PRR=1MHz$, duty cycle 50%.

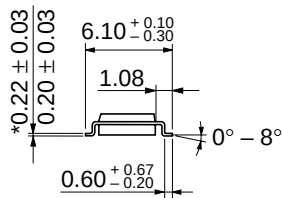
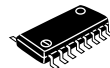
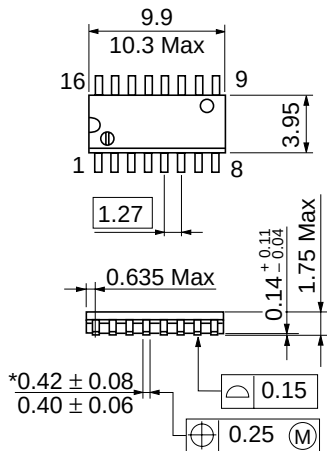


Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1.07 g



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.24 g



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.15 g

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